

List of Participants

ITU Workshop on AI and multimedia: Exploration of new frontiers and cross-SDO synergy
18 January 20212

	Name	Country	Organization
Host Details			
1.	Gent Bajrami (Tsb Events)	Switzerland	International Telecommunication Union (ITU)
2.	Gifty Amoah (Tsb Events)	Switzerland	International Telecommunication Union (ITU)
3.	Krista Garnace (Tsb Events)	Switzerland	International Telecommunication Union (ITU)
Host Details			
4.	Kenji Kondo	Japan	Sony Group Corporation
5.	Jung-Ah Choi	South Korea	LG Electronics
6.	Masahito Kawamori	Japan	Keio University
7.	Aynur Babayeva	Azerbaijan	Ministry of Digital Development and Transport
8.	Elena Alshina	Germany	Huawei Technologies Dusseldorf GMBH
9.	Mei Yan	China	CAICT
10.	Dayun Nam	South Korea	ETRI
11.	Seungwook Hong	U.S.A.	Nokia
12.	Noah Luo	Switzerland	Huawei
13.	Gi-Mun Um	Republic of Korea	ETRI
14.	Yuan Zhang	China	China Telecom
15.	Fabrice Urban	France	Interdigital
16.	Stuart Perry	Australia	University of Technology Sydney
17.	Enhui Liu	China	Huawei Technologies Co. Ltd.
18.	Touradj Ebrahimi	Switzerland	EPFL
19.	Mamtha N	India	Samsung Research Institute Bangalore
20.	Alexey Filippov	U.S.A.	Ofinno LLC
21.	Tanni Das	Bangladesh	Gachon University
22.	Thomas Guionnet	France	Ateme
23.	Fernando Pereira	Portugal	IST-IT
24.	Vasily Rufitskiy	U.S.A.	Ofinno
25.	Andrew Segall	U.S.A.	Sharp Labs of America
26.	Islom Pardayev	Uzbekistan	Unicon.uz
27.	Werner Bailer	Austria	Joanneum Research
28.	Ching-Yeh Chen	China	MediaTek
29.	Konstantin Lazaridis	Uzbekistan	Unicon.uz
30.	Seong-Ho Jeong	South Korea	Hankuk University of Foreign Studies
31.	Sung-Chang Lim	South Korea	ETRI
32.	Tianyu Dong	South Korea	Hanyang University
33.	Shunsuke Iwamura	Japan	NHK
34.	Weimin Zhang	China	CAICT
35.	Takeshi Chujoh	Japan	Sharp Corporation
36.	Yuntao Wang	China	CAICT
37.	Lidong Xu	China	Intel China Research Center

38.	Zhipin Deng	China	Bytedance Inc.
39.	Dimitrie Margarit	U.S.A.	V-Silicon
40.	Hyon-Gon Choo	South Korea	ETRI
41.	FNU Hendry	U.S.A.	LG Electronics
42.	Gary Sullivan	U.S.A.	Microsoft Corp.
43.	Jonathan Gan	Australia	OPPO
44.	Martin Winken	Germany	Fraunhofer HHI
45.	Caiysen	China	Midea Group
46.	Heeji Han	Republic of Korea	Hanbat National University
47.	Yu-Chiao Yang	Taiwan	FG Innovation
48.	Olena Chubach	USA	MediaTek
49.	Toru Suneya	Japan	Canon
50.	Cheng-Yen Chuang	Taiwan	MediaTek
51.	Robert Skupin	Germany	Fraunhofer HHI
52.	Masato Shima	Japan	Canon Inc.
53.	Xiangyu Qu	China	ZJDH
54.	Azamov Temur MITC	Ўзбекистан	The Ministry For Development Of Information Technologies And Communications Of The Republic Of Uzbekistan
55.	Junghak Nam	KR	LGE
56.	Daniel Becking	Germany	Fraunhofer HHI
57.	Chih-Yuan Chen	Taiwan	FG Innovation
58.	Min Woo Park	South Korea	Samsung Electronics
59.	Tom Starr	U.S.A.	Futurewei
60.	Sean McCarthy	U.S.A.	Dolby Laboratories, Inc.
61.	Hyungmin Roh	South Korea	Samsung Research
62.	Alireza Aminlou	Finland	Nokia
63.	Han Gao	U.S.A.	Kwai Inc.
64.	Yan Ye	U.S.A.	Alibaba
65.	Bart Kroon	Netherlands	Philips
66.	Jongho Kim	Rep. of Korea	ETRI
67.	Xinwei Li	CN	alibaba
68.	Leki Choden	Bhutan	Ministry of Information and Communications
69.	Vadim Seregin	U.S.A.	Qualcomm
70.	Masanori Fukada	Japan	Canon
71.	Emmanuel Thomas	Netherlands	Xiaomi
72.	Shih-Chun Chiu	Taiwan	MediaTek
73.	René van der Vleuten	Netherlands	Philips
74.	Philippe Guillotel	France	InterDigital
75.	Mitra Damghanian	Sweden	Ericsson
76.	Hongtao Wang	U.S.A.	Qualcomm Technologies, inc.
77.	Xiongwei Jia	China	China Unicom
78.	ying gao	中国	zte
79.	Yu-Chieh Nien (郁潔粘)	TW/Hsinchu	思羈科股份有限公司
80.	Michael Schäfer	Germany	Fraunhofer HHI
81.	Zhihuang Xie	China	OPPO
82.	Gerhard Tech	Germany	Fraunhofer HHI

83.	Yu-Chi Su	Taiwan	Mediatek
84.	Oh-Jin Kwon	Rep. of Korea	Sejong Univ.
85.	edouard francois	France	InterDigital
86.	Dong Tian	U.S.A.	InterDigital
87.	Jacob Ström	Sweden	Ericsson
88.	Sungryeul Rhyu	Korea	Samsung
89.	Philipp Merkle	Germany	Fraunhofer HHI
90.	Jin Heo	Republic of Korea	Hyundai motor group
91.	hyoungjin kwon	South Korea	ETRI
92.	Yuling Hsiao	U.S.A.	MediaTek
93.	Pejman Mowlae	Denmark	GN Audio (Jabra)
94.	Takaaki Ishikawa	Japan	Canon Inc.
95.	Daehyeok Gwon	Republic of Korea	Hanbat National University (HNU)
96.	Chih-Yao Chiu	U.S.A.	MediaTek - US
97.	Joonsoo Kim	Republic of Korea	ETRI
98.	Yangwoo Kim	South Korea	Samsung Electronics
99.	Detlev Marpe	Deutschland	Fraunhofer HHI
100.	Luoming ZHANG	瑞士	Huawei
101.	Sunghee Wi	South Korea	ETRI
102.	UZB Djaborova	Узбекистан	ГУП "UNICON.UZ"
103.	Xue Zhang	China	DaHua
104.	Jonathan Pfaff	Germany	Fraunhofer HHI
105.	Arshnoos Nakhaei	Iran	Faculty of electrical and computer engineering , University Of Sistan And Baluchestan
106.	Zhi Zhang	Germany	Qualcomm
107.	Tomohiro Ikai	日本	Sharp Corporation
108.	Reji Mathew	Australia	UNSW
109.	Hossein Golestani	Germany	Qualcomm
110.	Alireza Zare	Finland	Nokia
111.	Rickard Sjöberg	Sweden	Ericsson
112.	Tao Lin	China	Tongji University
113.	Christopher Hollmann	Sweden	Telefon AB LM Ericsson
114.	Yeshwant Muthusamy	United States	Immersion Corporation
115.	Franck Denoual	France	Canon Research Centre France
116.	Pierre Hellier	France	Interdigital
117.	Koohyar Minoo	Iran	Self Rep
118.	Herve Le Floch	France	Canon Research France
119.	Keming Cao	U.S.A.	Qualcomm
120.	Martin Pettersson	Sweden	Ericsson AB
121.	Zizheng Liu	China	Tencent
122.	Ambarish Natu	Australia	Department of Infrastructure
123.	Chuan Zhou	China	Vivo
124.	Leanne (吴龙梅)	China	Midea Group
125.	Paul Haase	Germany	Fraunhofer Heinrich-Hertz-Institute (HHI)
126.	Alexandre Zaghetto	U.S.A.	Sony
127.	Sunghan Kim	South Korea	ETRI
128.	Marius Preda	France	IMT
129.	Ping Wu	United Kingdom	ZTE
130.	Jack Enhorn	Sweden	Ericsson
131.	Jai Young Oh	South Korea	Hanyang University
132.	Yukinobu Yasugi	Japan	Sharp
133.	Yoichi Yagasaki	Japan	Sony Corporation
134.	Jungwon Kang	South Korea	ETRI
135.	Amir Said	United States	Qualcomm Technologies, Inc.

136.	Chris Rosewarne	Australia	Canon Australia
137.	Bilel Jamoussi	Switzerland	International Telecommunication Union
138.	Shengyang Zhao	中国	Alibaba
139.	Yu-Wen Huang	Taiwan	MediaTek
140.	Guillaume Boisson	France	InterDigital
141.	Ya Chen	France	InterDigital
142.	Han Zhang	China	Tencent
143.	Karsten Mueller	Germany	Fraunhofer HHI
144.	Ramin Youvalari	Finland	Nokia
145.	Patrice Rondao Alface	Belgium	Nokia
146.	Gwangsoon Lee	Korea	ETRI
147.	Kiyofumi Abe	Japan	Panasonic
148.	Mehdi Rezaei	Iran	University of Sistan and Baluchestan
149.	Jie-Ru Lin	U.S.A.	ITRI
150.	Sergey Ikonin	Russia	Huawei
151.	Zhuoyun Zhang	China	Tencent
152.	Julien Lemotheux	France	Orange
153.	Fabrice Le Léannec	France	Xiaomi
154.	Сергеев Борис	Россия	Региональное содружество в области связи (PCC)
155.	Hoda Roodaki	Iran	K. N. Toosi university of technology
156.	Kambiz Homayounfar	Switzerland	RayShaper SA
157.	Hong-Hui Chen	Taiwan	Mediatek
158.	Kiho Choi	South Korea	Gachon University
159.	Joao Ascenso	Portugal	IST
160.	Yasser Syed	U.S.A.	Comcast
161.	Eduardo Juarez	Spain	Universidad Politecnica de Madrid
162.	Lu Yu	China	Zhejiang University
163.	Shuang Peng	China	DaHua
164.	Tomas Borges	Brasil	University of Brasilia (UNB)
165.	Gun Bang	South Korea	ETRI
166.	Srinivas Gudumasu	Canada	InterDigital
167.	Antonio Pinheiro	Portugal	UBI & IT
168.	Denis Fortin	France	Vitec
169.	Maxim Sychev	Russia	Huawei Technologies
170.	Ugyen Rangdrol	Bhutan	Ministry of Information and Commitments
171.	Chih-Yu Teng	U.S.A.	FG Innovation
172.	Gauthier Lafruit	Belgium	ULB-LISA
173.	Jens-Rainer Ohm	Germany	RWTH Aachen
174.	Simao de Campos Neto	Switzerland	ITU
175.	Eric Yip	South Korea	Samsung Electronics
176.	Kiran Misra	U.S.A.	Sharp Labs of America
177.	Peng Yin	U.S.A.	Dolby
178.	Faiz Ullah	South Korea	Sejong University, Seoul
179.	Christopher Schroers	Switzerland	Disney Research
180.	Jingying Gao	Singapore	Panasonic
181.	Sofia Dimitriadi	Germany	Fraunhofer IIS
182.	Cheng Huang	China	ZTE Corporation
183.	Guillaume Laroche	France	Canon
184.	Imed Bouazizi	United States	Standards
185.	Xiaozhong Xu	United States	Tencent
186.	Wenhao Zhang	China	Disney Streaming
187.	Franck Galpin	France	InterDigital Inc
188.	Xinrong Zhang	中国	Tsinghua University

189.	Federico Lo Bianco	France	InterDigital
190.	Ruoyang Yu	Sweden	Ericsson
191.	Philippe Bordes	France	Interdigital
192.	Shunsuke Iwamura	Japan	NHK
193.	Sophie Pientka	Germany	Fraunhofer HHI
194.	Wei Jiang	U.S.A.	Alibaba Group
195.	Ville-Veikko Mattila	Finland	Nokia
196.	Ohji Nakagami	Japan	Sony group corporation
197.	Nabajeet Barman	United Kingdom	Brightcove
198.	Kenneth Andersson	Sweden	Ericsson
199.	Takehito Miyazawa	Japan	NTT
200.	Kwan-Jung Oh	Korea	ETRI
201.	Shih-Ta Hsiang (向時達)		
202.	Jin Young Lee	Korea	ETRI
203.	Velibor Adzic	U.S.A.	OP Solutions
204.	Du Liu	Sweden	Ericsson
205.	Yolanda Prieto	U.S.A.	Prisua
206.	Qiuting Li	China	ZTE Corporation
207.	Ning Zong	China	Huawei
208.	Angelo Bruccoleri	Italy	RAI
209.	梓怡 曾	China	UESTC
210.	Dong Wang	中国	OPPO
211.	Dash Zhiwei Liu	德国	China Telecom Duschland GmbH
212.	Karsten Suehring	Germany	Fraunhofer HHI
213.	Han Boon Teo	Singapore	Panasonic R&D Center Singapore
214.	David Filip	Ireland	Huawei Technologies
215.	Ling Li	U.S.A.	Tencent
216.	Ismael Arribas	Spain	Kunfud
217.	Michel Bätz	Germany	Fraunhofer IIS
218.	Sunmi Yoo	Korea	LG Electronics
219.	Gwenaelle Marquant	France	Interdigital
220.	PoHan Lin	U.S.A.	Qualcomm
221.	Neda Dolati	Iran	Iran University of Science & Technology
222.	Saurabh Puri	Canada	Interdigital
223.	Jörn Erbguth	Switzerland	University of Geneva
224.	Kazunori Tanikawa	Japan	NICT
225.	Ru-Ling Liao	China	Alibaba group
226.	Ardavan Elahi	Iran	Avan
227.	Srivatsa Prativadibhayankaram	Germany	Fraunhofer IIS
228.	Naeri Park	Korea	LGE
229.	Reza Sharifi	Iran	RAI
230.	Karam Naser	France	InterDigital
231.	Omid Fatemi	Iran	U. of Tehran
232.	Johannes Sauer	Germany	Huawei
233.	Tae Meon Bae	U.S.A.	Ofinno
234.	Didier Doyen	France	Interdigital
235.	Chirag Pujara	India	Samsung IN
236.	anubhav singh	India	Samsung Research India, Bangalore
237.	Hyunkoo Yang	Korea	Samsung Electronics Co., Ltd.
238.	Hualong Yu	China	Zhejiang University
239.	Luis Cruz	Portugal	University of Coimbra
240.	Hong-Jheng Jhu	U.S.A.	Kwai Inc.
241.	Yingbin Wang	China	Tencent
242.	Yan Shen	China	China Telecom

243.	Martyn Lee	United Kingdom	Sky UK
244.	Alireza Shamshiri	Iran	MCI
245.	Charith Abhayaratne	United Kingdom	The University of Sheffield
246.	Saydiakhrol Saydiakbarov Uzb	Ўзбекистан	UNICON.UZ
247.	Mehri Yahyaei	Iran	Research centre of informatics industries
248.	Hideo Imanaka	日本	NTT-AT
249.	Zhuoyi Lv	China	vivo
250.	Liping Zhao	China	Shaoxing University
251.	Bertrand Chupeau	France	Interdigital R&D France
252.	Maciej Pedzisz	United Kingdom	Synaptics
253.	Oscar Avellaneda	Canada	ISED Canada
254.	Gilles Teniou	France	Tencent
255.	Jean Le Feuvre	France	Telecom Paris
256.	Diego Gibellino	Italy	Telecom Italia
257.	Vincent Affleck	UK	DCMS
258.	Yaxian Bai	China	ZTE Corporation
259.	Nozir Tukhtamurodov	Uzbekistan	The Ministry for Development of Information
260.	Jangwon Choi		
261.	Atanas Boev	Germany	Huawei Technologies Duesseldorf
262.	Tzu-Der	台灣	MediaTek Inc.
263.	Quockhanh Dinh	Korea	Samsung Research
264.	Pavel Nikitin	France	InterDigital
265.	Bastiaan Quast	Switzerland	ITU
266.	Yokota Akane	Japan	Canon
267.	Christian Timmerer	Austria	AAU
268.	Minsoo Park	Korea	Samsung Electronics
269.	Pritha Ganguly	India	Samsung
270.	Zhenyu Dai	China	OPPO
271.	Shih-Ta Hsiang	Taiwan	Multimedia Department
272.	Yubin Hu	China	Tsinghua University
273.	Jiancong Luo	U.S.A.	Apple
274.	Wei Wang	U.S.A.	Alibaba
275.	Chih-Hsuan Lo	Taiwan	MediaTek - US
276.	Mylene Farias	Brazil	UnB
277.	Aous Naman	Australia	UNSW
278.	Nisha Bhaskar	Germany	Fraunhofer IIS
279.	Vinod Kumar Malamal Vadakital	Finland	Ofinno
280.	Shimpei Nemoto	Japan	NHK
281.	Hamed Tavakoli	Finland	Nokia Technologies
282.	Junichi Hara	Japan	Waseda Univ.
283.	Arian Koster	Netherlands	TNO
284.	Miran Choi	South Korea	ETRI
285.	Bohyeon Hwang	South Korea	Sejong University
286.	Mohamad Raad	Lebanon	Lebanese International University
287.	Yipeng Zhang	China	Tencent
288.	Tung Nguyen	Germany	Fraunhofer HHI
289.	Loginov Fedor	China	Huawei
290.	Minseok Lee	South Korea	Kyung Hee University
291.	Stefano Battista	Italia	UNIVPM
292.	Hassane Guermoud	France	Interdigital
293.	Tianying Ji	U.S.A.	Sharp Labs of America
294.	Jinwoo Jeong	Korea	KETI
295.	Hang Huang	China	OPPO
296.	Sungjei Kim	South Korea	Korea Electronics Techology Institute

297.	Alexandre Rouxel	France	European Broadcasting Union
298.	Zhigao Fang (致高方)	中国	浙江大学
299.	Youngseop Kim	Korea	Dankook university
300.	Damian Ruiz Coll	U.S.A.	OFINNO
301.	Seong Yong Lim	Korea South	ETRI
302.	Shaowei Xie	China	ZTE China
303.	Francesco Cricri	Finland	Nokia
304.	Miska Hannuksela	Finland	Nokia
305.	Yanghao Li	China	Tsinghua Univ.
306.	Samira Afzal	Austria	University of Klagenfurt
307.	Mehrdad Teratani	Belgium	Université Libre de Bruxelles
308.	Roberto Hirayama	Brazil	ANATEL
309.	Chen-Yen Lai	U.S.A.	MediaTek.Inc
310.	Joe Zhao	Germany	NA
311.	Aviral Agrawal	India	SRIB
312.	Reham ElMayet	Egypt	League of Arab States
313.	Tong Wu	China	China Telecommunications Corporation
314.	Yong HE	U.S.A.	Qualcomm
315.	Luhang Xu	China	OPPO
316.	Pankaj Topiwala	USA	FastVDO LLC
317.	Sheng-Po Wang	台灣	
318.	Lulin Chen	U.S.A.	MediaTek
319.	Mohsen Kazemifard	Iran	Irib
320.	Ajay Luthra	U.S.A.	Picssel Labs
321.	Woonki Park	Korea	SKKU, NaverZ
322.	Hiu-Fai Chan	U.S.A.	Intel Corporation
323.	Mariam Torosyan	Armenia	Ministry of High-Tech Industry
324.	Jianan Lu	China	Zhuiyi
325.	Morteza Yadegari	Iran	Tehran university
326.	Hahyun Lee	Korea	ETRI
327.	Linyongbing	China	Huawei
328.	Guoqing Wu	Chinese	Bytedance
329.	Guo Jianling	china	Baidu
330.	Walt Husak	U.S.A.	Dolby Labs
331.	Peter Raeymaekers	Germany	European Patent Office
332.	Heiko Sparenberg	Germany	Fraunhofer IIS
333.	Haoping Yu	U.S.A.	OPPO
334.	Milos Radosavljevic	France	Interdigital
335.	Young Lee	U.S.A.	Ofinno
336.	Marco Carugi	France	Huawei Research Europe
337.	Hu Chen	Germany	Huawei Technologies Duesseldorf GmbH
338.	Xianglin Wang	U.S.A.	Kwai Inc.
339.	Andrew Krupiczka	U.S.A.	Disney
340.	Ali Zandifar	U.S.A.	Dolby Lab Inc.
341.	Wen Gao	U.S.A.	Tencent
342.	Tsung-Hua Li	U.S.A.	FG Innovation
343.	Sarra Rebhi	Tunisia	Office National de la Télédiffusion Tunisie
344.	Patrice Onno	France	Canon Research Centre France
345.	Hyeongmunjang	South Korea	LGE
346.	Hyomin Choi	U.S.A.	Interdigital
347.	Hamid Azadegan	Iran	IRIB
348.	Krishna Rapaka	U.S.A.	Apple
349.	Biao Wang	Germany	Huawei Technology Desseldorf GmbH
350.	Fabien Racape	U.S.A.	Interdigital

351.	Mahmoud Hashemi	Iran	University of Tehran
352.	Hong-Chang Shin	Republic of Korea	ETRI
353.	Navid Homayouni	Iran	Satra
354.	Dan Grois	Israel	Comcast
355.	Honglei Zhang	Finland	Nokia
356.	Sobirjon Radjabov	Uzbekistan	Research Institute For Development Of Digital Technologies And Artificial Intelligence
357.	Pierre Andrivon	France	Xiaomi
358.	Liqiang Wang	China	Tencent
359.	Sangwoon Kwak	South Korea	ETRI
360.	Yuwei Wang	China	Institute of Computing Technology Chinese Academy of Sciences
361.	Yajun Zhang	China	Tencent
362.	Favour Borokini	Nigeria	Pollicy
363.	Changyue Ma	China	Alibaba Group
364.	Yong Yan	U.S.A.	Poly
365.	Nan Hu	U.S.A.	Qualcomm
366.	Marc Antonini	France	CNRS
367.	Han Zhu	China	Wuhan University
368.	Alexander Karabutov	Russia	Huawei
369.	Nushik Petrosyan	Armenia	Ministry of High-Tech Industry of RA
370.	Soohyun Kim	Korea	Korea University
371.	Kyungah Kim	South Korea	Samsung
372.	Pascal Le Guyadec	France	InterDigital
373.	Atsuro Ichigaya	Japan	NHK
374.	Hu Doudou	China	China Telecom
375.	Emmanouil Potetsianakis	NL	TNO
376.	Chad Fogg	U.S.A.	MovieLabs
377.	Byeongdoo Choi	U.S.A.	Amazon
378.	Ibrahim Mohamud	Somalia	National Communications Authority of Somalia
379.	Ming Li	China	OPPO
380.	Yin Zhao	China	Huawei Technologies
381.	Chaoyi Lin	China	Bytedance Inc.
382.	Heiko Schwarz	Germany	Fraunhofer HHI
383.	Keiichiro Takada	Japan	Sharp Corporation
384.	Sylvain Kervadec	France	Orange
385.	Andre Souto	Belgium	ULB
386.	Ekaterina Lyskovtseva	Russia	RCC
387.	Wenqi Ji	China	Tsinghua University
388.	Chris Varekamp	The Netherlands	Philips Research
389.	Jie Chen	China	Alibaba
390.	Philippe De Lagrange	France	Interdigital
391.	Kohtaro Asai	Japan	Mitsubishi Electric Corporation
392.	Tomonori Hashimoto	Japan	Sharp Corporation
393.	Mohammad Amin Hojjati Kermani	Iran	IGMC
394.	Woong Lim	KR	ETRI
395.	Gurdeep Singh	Canada	InterDigital
396.	Scott Houchin	U.S.A.	The Aerospace Corporation
397.	Adrian Browne	United Kingdom	Sony
398.	Klaas Schueuer	Germany	Dolby
399.	Yan Wang	China	Sensetime
400.	Kazushi Sato	Japan	OPPO
401.	Wen-Chun Lin	U.S.A.	Mediatek
402.	Cornelius Hellge	Germany	Fraunhofer HHI

403.	Thomas Schierl	Germany	Fraunhofer HHI
404.	Honglian Wei	China	OPPO
405.	Sami Meddeb	Tunisia	Samart Tunisia tehnoparc
406.	Brian Lee	U.S.A.	Dolby Laboratories
407.	Mahmood Zemari	Iran	Irib
408.	Kaoru Mizuno	Switzerland	ITU
409.	Xavier Ducloux	France	Harmonic
410.	Franck Aumont	France	Interdigital
411.	Sachin Deshpande	U.S.A.	Sharp Labs of America
412.	Krit Panusopone	U.S.A.	Nokia
413.	Jiahao Pang	U.S.A.	InterDigital
414.	Yonghwan Lee	South Korea	Wonkwang university
415.	Anand Meher Kotra	Germany	Qualcomm
416.	Ahmed Hamza	Canada	InterDigital Canada
417.	Muhammed Coban	U.S.A.	Qualcomm
418.	Yun Li	Sweden	Ericsson
419.	Farzad Zargari	Iran	Research Institute for ICT
420.	Muhammad Lodhi	U.S.A.	InterDigital
421.	Kenji Kondo	Japan	Sony Group Corporation
422.	Jung-Ah Choi	South Korea	LG Electronics
423.	Masahito Kawamori	Japan	Keio University
424.	Aynur Babayeva	Azerbaijan	Ministry of Digital Development and Transport
425.	Elena Alshina	Germany	Huawei Technologies Dusseldorf GMBH